EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	798	438/460.ccls.	USPAT	OR	ON	2008/08/15 12:56
L2	373	438/114.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 13:07
L3	1476	438/464.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 13:08
L4	68	((photothermal adj conversion or lthc) and layer) and heat and decompos$4 and irradiat$4.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 13:15
L5	14	(photothermal adj conversion adj layer) and heat and decompos$4 and irradiat$4.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 13:15
L6	2	(photothermal adj conversion adj layer) and heat and decompos$4 and irradiat$4 and circuit and pattern and grind$3 and dic$3 and chip.clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/08/15 13:18
L7	1533	257/e21.499.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 13:26
S1	2825	438/455.ccls. or 438/458.ccls. or 438/459. ccls. or 438/460.ccls. or 438/464.ccls. or 438/465.ccls.	USPAT	OR	ON	2007/08/27 15:44
S2	1852	438/455.ccls. or 438/458.ccls. or 438/459. ccls.	USPAT	OR	ON	2007/08/27 15:43

S3	1242	438/460.ccls. or 438/464.ccls. or 438/465. ccls.	USPAT	OR	ON	2007/08/27 15:44
S4	1583	S2 not S3	USPAT	OR	ON	2007/08/27 15:44
S5	1784	S1 and ((grind$3 or thin$4) with (wafer or substrate))	USPAT	OR	ON	2007/08/27 15:45
S7	1327	S2 and ((dic$3 or cut$4 or separat$3) with (wafer or substrate))	USPAT	OR	ON	2007/08/27 15:54
S8	124	S3 and ((resin or adhesive or glue) with light)	USPAT	OR	ON	2007/08/27 15:51
S9	690	S3 and (irradiat$3 or radiat$3 or photothermal or UV or light or energy)	USPAT	OR	ON	2007/08/27 15:52
S10	64559	((grind$3 or thin$4) with wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 15:49
S11	1482	S5 and ((dic$3 or cut$4 or separat$3) with (wafer or substrate))	USPAT	OR	ON	2007/08/27 15:50
S12	127	S7 and ((resin or adhesive or glue) with light)	USPAT	OR	ON	2007/08/27 15:52
S13	944	S7 and (irradiat$3 or radiat$3 or photothermal or UV or light or energy)	USPAT	OR	ON	2007/08/27 15:52
S14	152	S11 and ((resin or adhesive or glue) with light)	USPAT	OR	ON	2007/08/27 15:52
S15	152	S14 and (irradiat$3 or radiat$3 or photothermal or UV or light or energy)	USPAT	OR	ON	2007/08/27 15:52
S17	76	S15 and ((irradiat$3 or radiat$3 or photothermal or UV or light or energy) with resin)	USPAT	OR	ON	2007/08/28 11:09
S18	21348	S10 and ((dic$3 or cut$4 or separat$3) with wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 15:56
S19	1372	S18 and ((resin or adhesive or glue) with (light or UV))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/29 08:04

S20	99	S19 and (photothermal or light adj heat)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 16:00
S21	1244	S19 and ((photothermal or light adj heat) with conversion layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 16:04
S22	962	S21 and (laminat$4 or coat$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 16:05
S23	522	S22 and vacuum	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 16:05
S24	74	S23 and (scribe adj line$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 16:26
S25	180	S23 and (scribe adj line$2 or street$)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/27 16:26
S26	1	"7201969"	USPAT	OR	ON	2007/08/28 12:18
S27	0	EP0571649	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/28 12:32

S28	6	"0571649"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/28 12:45
S29	11	"4037014"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/28 12:54
S30	128	"6214520"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/28 15:30
S31	4	"7201969"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/28 16:58
S32	9	"6620649"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 09:23
S34	2	"200030506"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/28 15:30
S35	35	"0135457"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/28 14:14

S39	35	"0135457"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/28 14:15
S40	48	"0030506"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/28 14:15
S51	6903939	"20040185639" A1	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/29 08:04
S52	2	"20040185639"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/29 08:04
S53	34	"5414297"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/29 10:14
S54	9	"6007650"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/29 10:22
S55	10	"4818323"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/29 13:26

S56	7	"6551906"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2007/08/29 13:26
S57	1168	(438/458).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/01/31 13:33
S58	130684	photo$1thermal or light near4 heat	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 13:42
S59	91	S57 and S58	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 13:43
S60	0	(438/273.1).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/01/31 13:57
S61	145	(438/273).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/01/31 13:57
S62	62	"5476566"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 13:59
S63	52	"6284425"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 13:59
S64	36	"6358664"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 13:59

S65	2	"20010018404"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 14:00
S66	3	"03017363"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 14:00
S67	8	"1255522"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 14:00
S68	6	"0571649"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 14:00
S69	67538	((grind$3 or thin$4) with wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/01/31 15:30
S70	22459	S69 and ((dic$3 or cut$4 or separat$3) with wafer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/01/31 15:30
S71	1484	S70 and ((resin or adhesive or glue) with (light or UV))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/01/31 15:30

S72	1352	S71 and ((photothermal or light adj heat) with conversion layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/01/31 15:30
S73	1048	S72 and (laminat$4 or coat$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/01/31 15:30
S74	140	"6214520"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/01/31 15:37
S75	715	(438/690).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/01/31 16:08
S76	1185	(438/460).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/01/31 16:20
S77	4	"03060972"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/01/31 16:46
S78	716	(438/464).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/01/31 16:54
S79	337	(438/114).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/02/10 13:42
S80	717	(438/464).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/02/10 13:42
S81	743	(257/e21.499).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/02/10 13:43
S82	2	"6979593"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/02/10 13:45
S83	1	"20030188776"	USPAT	OR	ON	2008/02/11 16:42

S84	338	(438/114).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/02/14 07:57
S85	338	S84	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/02/14 07:57
S86	719	(438/464).CCLS.	US-PGPUB; USPAT	OR	OFF	2008/02/14 10:18
S87	719	S86	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/02/14 10:18
S88	2	"7226812"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/02/14 10:49
S89	52	"6284425"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	OFF	2008/02/14 12:53
S90	4673711	((photothermal or light adj heat) with conversion layer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2008/08/13 16:43
S91	1012076	((resin or adhesive or glue) with light or heat)	USPAT	OR	ON	2008/08/13 16:49